

Title (en)

GOLD ELECTROPLATING SOLUTION AND ITS USE FOR ELECTRODEPOSITING GOLD WITH AN AGED APPEARANCE

Title (de)

GOLDGALVANISIERUNGSLÖSUNG UND IHRE VERWENDUNG ZUR GALVANISCHEN ABSCHIEDUNG VON GOLD MIT GEALTERTEM AUSSEHEN

Title (fr)

SOLUTION D'ÉLECTRODÉPOSITION DE L'OR ET SON UTILISATION POUR L'ÉLECTRODÉPOSITION DE L'OR AVEC UN ASPECT VIEILLI

Publication

EP 4245893 A1 20230920 (EN)

Application

EP 22305294 A 20220315

Priority

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Abstract (en)

The invention relates to a gold electroplating solution comprising gold in the form of a complex with a compound of formula (I) or a salt thereof: $R^{1}S-Ar-CO^{2}H$ (I) Wherein : R^{1} is H, a C_{1-6} alkyl group or $-S-Ar-CO^{2}H$, Ar is, at each occurrence, independently, selected from a C_{6-10} arylene or a 5 to 10 membered heteroarylene group, notably a phenylene, a pyridinylene, a furanylene, a pyrrolylene, or a thienylene group.

IPC 8 full level

C25D 3/48 (2006.01); **C25D 3/62** (2006.01)

CPC (source: EP)

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Citation (applicant)

- CA 846796 A 19700714 - NOBEL FRED I, et al
- EP 0150439 A1 19850807 - LEARONAL UK PLC [GB]
- GB 1294309 A 19721025 - PMD CHEMICALS LTD
- GB 2039532 A 19800813 - INT GOLD CORP LTD
- WO 0039367 A2 20000706 - HALF TONE LIMITED [IE], et al
- GB 1526215 A 19780927 - SCHERING AG
- US 5277790 A 19940111 - MORRISSEY RONALD J [US]
- EP 1198623 A1 20020424 - HERAEUS GMBH W C [DE]
- EP 0582353 A1 19940209 - IBM [US]

Citation (search report)

- [XY] US 2007029206 A1 20070208 - ABE MIWA [JP], et al
- [XY] JP 2003226993 A 20030815 - ELECTROPLATING ENG
- [XY] US 6251249 B1 20010626 - CHEVALIER JEAN W [US], et al
- [XY] US 2017292200 A1 20171012 - HAYASHI KATSUNORI [JP]
- [X] JP H04110488 A 19920410 - ELECTROPLATING ENG
- [Y] US 2003111353 A1 20030619 - OHTANI YUTAKA [JP], et al
- [A] US 4532186 A 19850730 - SHIBAGAKI KAZUYOSHI [JP], et al

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